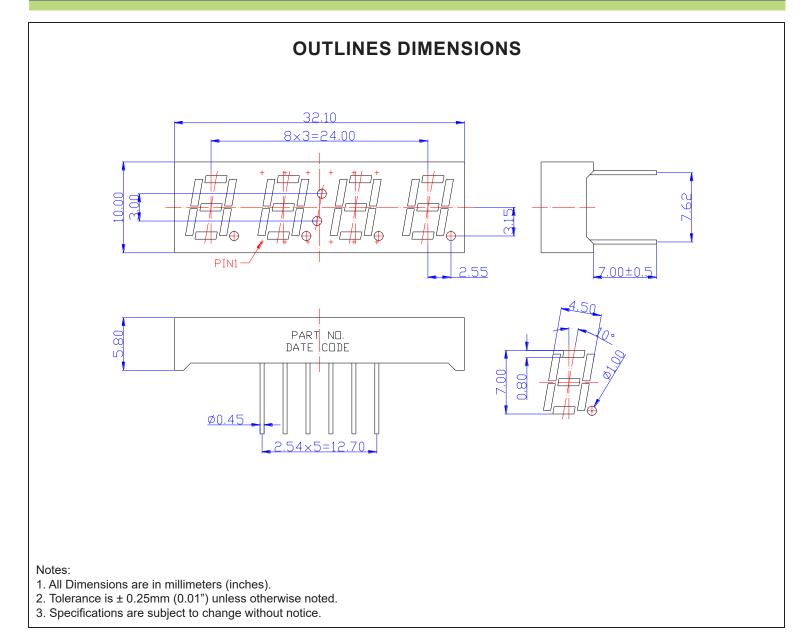


SPECIFICATIONS





Part Number	Chip Material	Color of Emission	Color of Emission Segment/Face	
CDQC28GT2WB	InGaN	Green	White/Black	Common Cathode





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit			
Power Dissipation	PD	120	mW			
Pulse Forward Current	lfp	120	mA			
Continuous Forward Current	lF	30	mA			
Reverse Voltage Segment	VR	5	V			
Operating Temperature Range	Topr	-25~+85	°C			
Storage Temperature Range	Тѕтс	-25~+85	°C			
IFP = Pulse Width \leq 10 ms, Duty Ratio \leq 1/10. Soldering Condition: 260 °C/ 5sec						

OPTICAL-ELECTRICAL CHARACTERISTICS

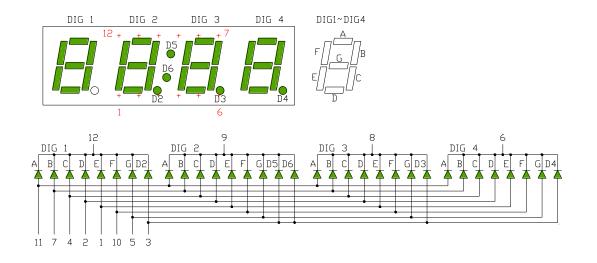
(TA=25°C)

Deremeter	Symbol	Test Condition	Value			Linit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	١v	l⊧ = 10mA	-	100	-	mcd
Forward Voltage	Vf	l⊧ = 20mA	-	3.2	-	V
Reverse Leakage Current	lr	V _R = 5V	-	-	10	μA
Dominant Wavelength	λD	l⊧ = 20mA	-	525	-	nm
Spectral Radiation Bandwidth	Δλ	l⊧ = 20mA	-	30	-	nm





TYPICAL INTERNAL EQUIVALENT CIRCUIT





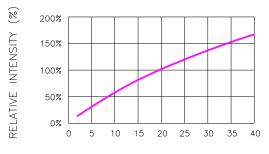


OPTICAL CHARACTERISTIC CURVES

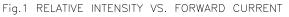


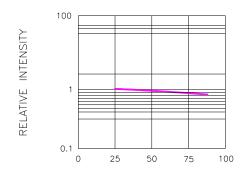
lF =mA

FORWARD CURRENT

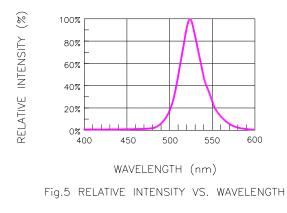


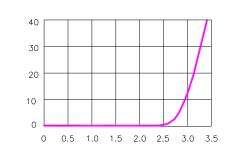
I_F@20mA (mA)



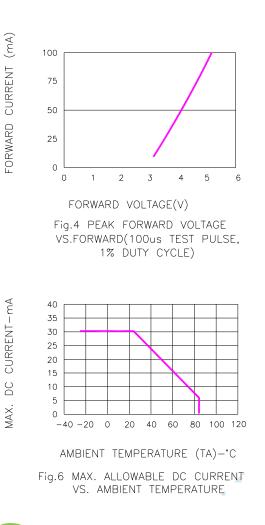


LEAD TEMPERATURE(°C) Fig.3 RELATIVE INTENSITY VS.LEAD TEMPERATURE (PULSED 20 mA; 300us PULSE,10ms PERIOD)





FORWARD VOLTAGE (V) Fig.2 FORWARD CURRENT VS. FORWARD VOLTAGE

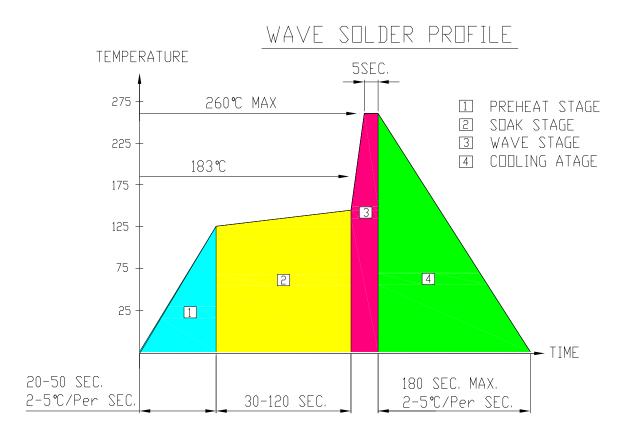






SOLDERING CONDITIONS – DISPLAY TYPE LED

RECOMMEND SOLDERING PROFILE



SOLDERING IRON

Basic spec is \leq 4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

REWORK

Customer must finish rework within ≦4 sec under 245°C.

